

Technical Bulletin



Solder plus Support

OAJ 2% Water Soluble Cored Wire Solder

DESCRIPTION

OAJ Flux Cored Solder Wire has been formulated with an innovative amine neutralized halide-activator system. This novel system offers a high activation level that provides rapid oxide removal and maximum capillary action, resulting in faster wetting on all surface finishes and plating. OAJ flux residues **MUST** be removed after soldering. IPC flux classification – ORH1.

FEATURES AND BENEFITS

- Excellent Wetting Properties
- High Activity Level
- Reduces Oxidation of Solder Iron Tip
- Residue Washes Easily with DI Water Alone
- Excellent Thermal Transfer
- ORH1 per IPC J-STD-004

ALLOY AVAILABILITY

OAJ Cored Wire is available in Sn/Pb, SAC305 and SN100C® alloys. Other alloys, diameters and spool sizes may be available upon request.

APPLICATION

Solder iron tip temperature should be between 350° - 400°C (650° - 750°F) for Sn63, Sn62 and Sn60 alloys, 370° - 425°C (700° - 800°F) for SN100C®, Sn/Ag and Sn/Ag/Cu (SAC305, SAC405, CASTIN, etc.) alloys.

CLEANING

Post-process residues can remain in place up to 8 hours*. Flux residue can be removed with normal tap water @ 38° - 60°C (100° - 140°F) with a DI water final rinse. Use of a pressurized spray cleaning system is suggested, but is not required.

*Environment and application dependent

STORAGE & SHELF LIFE

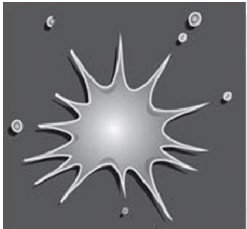
Store cored wire in a clean, dry area away from moisture and sunlight. Do not freeze this product.

Time	Conditions
3 years	Cool < 30°C (< 86°F) Dry < 75%Rh

HEALTH & SAFETY

Use with adequate ventilation and proper personal protective equipment. Refer to the accompanying Safety Data Sheet for any specific emergency information. Do not dispose of any hazardous materials in non-approved containers.

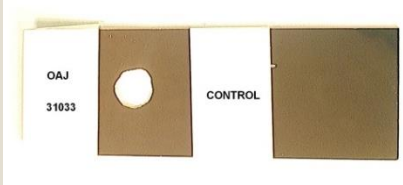
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SOLDER CONNECTION

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TEST DATA SUMMARY

Name	Test Method	Results	
IPC Flux Classification	J-STD-004	ORH1	
IPC Flux Classification	J-STD-004B 3.3.1	ORH1	
Name	Test Method	Results	Image
Copper Mirror	J-STD-004B 3.4.1.1 IPC-TM-650 2.3.32	High - > 50% Removal	
Corrosion	J-STD-004B 3.4.1.2 IPC-TM-650 2.6.15	Major Corrosion	Uncleaned
Quantitative Halides	J-STD-004B 3.4.1.3 IPC-TM-650 2.3.28.1	≥ 2.0% Typical	
Qualitative Halides, Silver Chromate	J-STD-004B 3.5.1.1 IPC-TM-650 2.3.33	Halides Detected	
Qualitative Halides, Fluoride Spot	J-STD-004B 3.5.1.2 IPC-TM-650 2.3.35.1	None Detected	
Surface Insulation Resistance	J-STD-004 3.4.1.4 IPC-TM-650 2.6.3.3	>100MΩ	Cleaned
Surface Insulation Resistance	J-STD-004B 3.4.1.4 IPC-TM-650 2.6.3.7	>100MΩ	Cleaned
Flux Solids, Nonvolatile Determination	J-STD-004B 3.4.2.1 IPC-TM-650 2.3.34	100% Typical	
Acid Value Determination	J-STD-004B 3.4.2.2 IPC-TM-650 2.3.13	104 ± 2.68 Typical	
Visual	J-STD-004B 3.4.2.5	White Solid	
Wetting	J-STD-005A 3.9 IPC-TM-650 2.4.45	PASS	
Fluoride	J-STD-004B IPC-TM-650	PASS	
Flux Spreading	J-STD-004B 3.7.2 IPC-TM-650 2.6.14.1	PASS	
Metal/Flux Content	J-STD-005A 3.4 IPC-TM-650 2.2.20	98% / 2%	
Spread	J-STD-004B 3.7.2 IPC-TM650 2.4.46	PASS	
Cleanliness	TM125-03	PASS	

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